

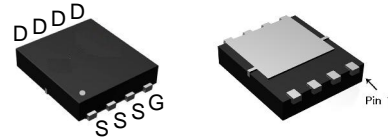
### Features

- 30V/54A,  
 $R_{DS(ON)} = 4.5m\Omega$  (typ.) @  $V_{GS} = 10V$   
 $R_{DS(ON)} = 6.5m\Omega$  (typ.) @  $V_{GS} = 4.5V$
- Reliable and Rugged
- Lower  $Q_g$  and  $Q_{gd}$  for high-speed switching
- Lower  $R_{DS(ON)}$  to Minimize Conduction Losses
- 100% UIS +  $R_g$  Tested
- Lead Free and Green Devices Available  
 (RoHS Compliant)

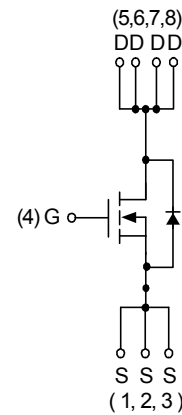
### Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

### Pin Description



PDFN3.3\*3.3-8L



N-Channel MOSFET

**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b>			
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ 54	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$ 54	
		$T_C=100^\circ\text{C}$ 21	
$I_{DM}^a$	Pulsed Drain Current	$T_C=25^\circ\text{C}$ 164	
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 26.6	W
		$T_C=100^\circ\text{C}$ 10.6	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State 4.7	$^\circ\text{C/W}$
$I_D^b$	Continuous Drain Current	$T_A=25^\circ\text{C}$ 13.8	A
		$T_A=70^\circ\text{C}$ 11	
$I_{DM}^b$	Pulsed Drain Current	$T_A=25^\circ\text{C}$ 34	
$P_D^b$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 1.73	W
		$T_A=70^\circ\text{C}$ 1.11	
$R_{\theta JA}^b$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$ 40	$^\circ\text{C/W}$
		Steady State 72	
$I_{AS}^c$	Avalanche Current, Single pulse	$L=0.1\text{mH}$ 31	A
$E_{AS}^c$	Avalanche Energy, Single pulse	$L=0.1\text{mH}$ 48	mJ

Note a : Pulse width is limited by max. junction temperature.

Note b :  $R_{\theta JA}$  steady state  $t=999\text{s}$ .

Note c : UIS tested and pulse width limited by maximum junction temperature  $150^\circ\text{C}$  (initial temperature  $T_J=25^\circ\text{C}$ ).

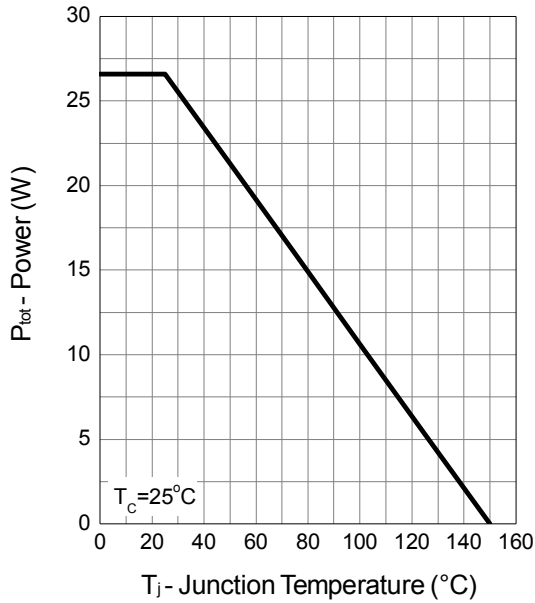
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30	-	-	V
$BV_{DSSst}$	Drain-Source Breakdown Voltage (transient)	$V_{GS}=0V, I_{D(av)}=20A$ $T_{case}=25^\circ\text{C}, t_{transient}=100ns$	34	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ\text{C}$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.5	1.8	2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^d$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=12A$	-	4.5	6	m $\Omega$
		$T_J=125^\circ\text{C}$	-	6	-	
		$V_{GS}=4.5V, I_{DS}=9A$	-	6.5	8	
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=10A$	-	16	-	S
<b>Diode Characteristics</b>						
$V_{SD}^d$	Diode Forward Voltage	$I_{SD}=10A, V_{GS}=0V$	-	0.8	1.1	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=5A, di_{SD}/dt=100A/\mu s$	-	11	-	ns
$t_a$	Charge Time		-	14	-	
$t_b$	Discharge Time		-	25	-	
$Q_{rr}$	Reverse Recovery Charge		-	13	-	
<b>Dynamic Characteristics</b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	1.8	3	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=15V,$ Frequency=1.0MHz	-	1150	-	pF
$C_{oss}$	Output Capacitance		-	160	-	
$C_{rss}$	Reverse Transfer Capacitance		-	137	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=15\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=1\Omega$	-	7.8	-	ns
$t_r$	Turn-on Rise Time		-	8.4	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	18	-	
$t_f$	Turn-off Fall Time		-	17	-	
<b>Gate Charge Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V,$ $I_{DS}=12A$	-	12	18	nC
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=4.5V,$ $I_{DS}=12A$	-	5.5	-	
$Q_{gth}$	Threshold Gate Charge		-	1.1	-	
$Q_{gs}$	Gate-Source Charge		-	1.9	-	
$Q_{gd}$	Gate-Drain Charge		-	2.2	-	

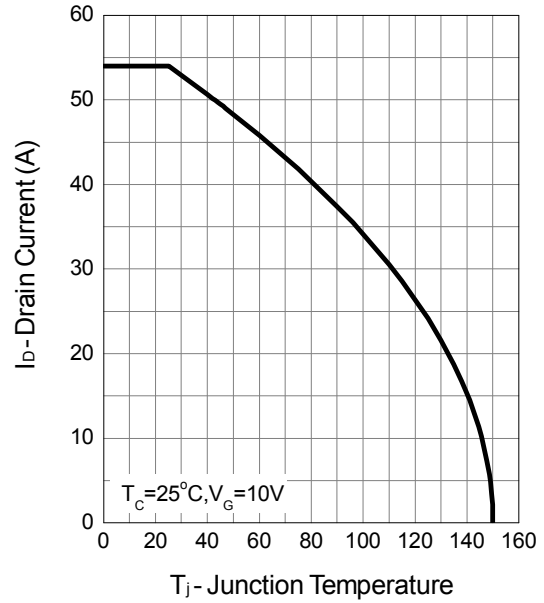
 Note d : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

### Typical Operating Characteristics

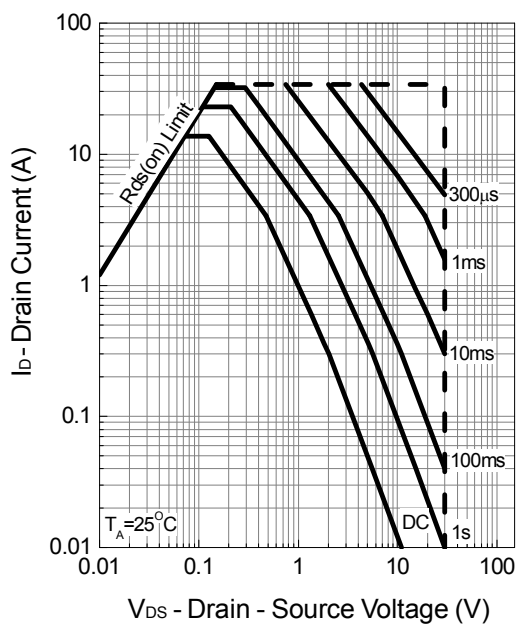
**Power Dissipation**



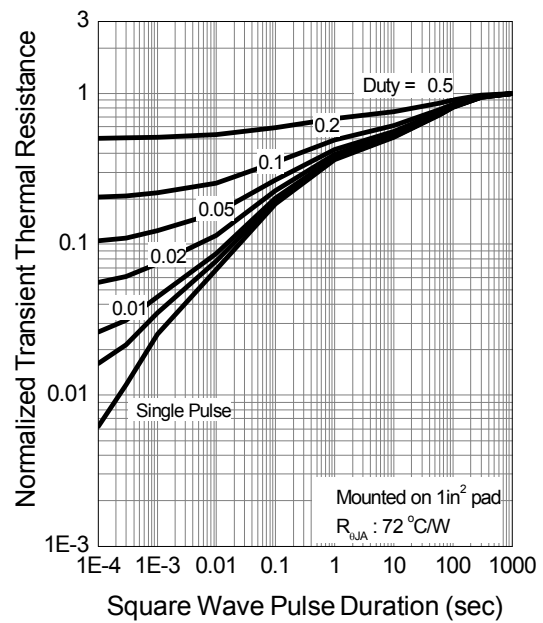
**Drain Current**



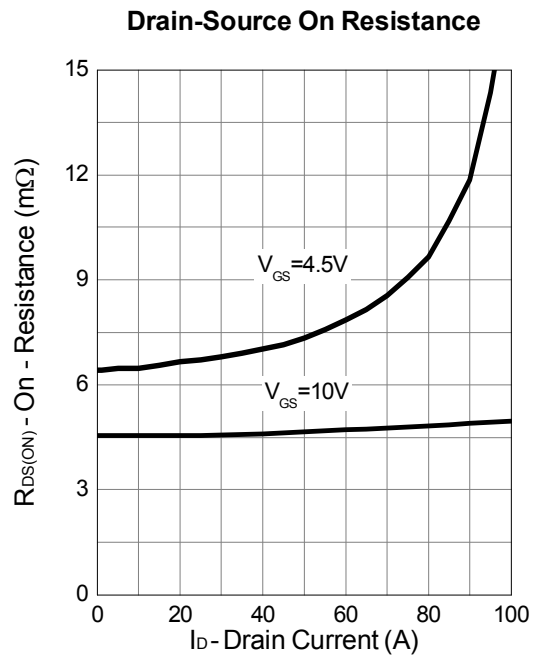
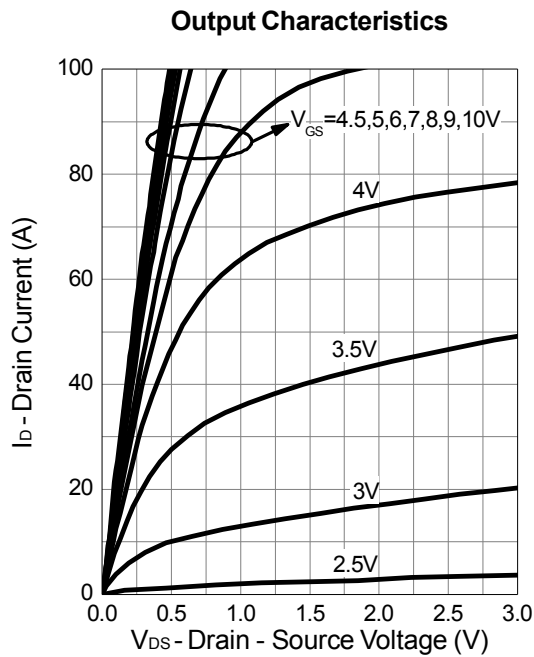
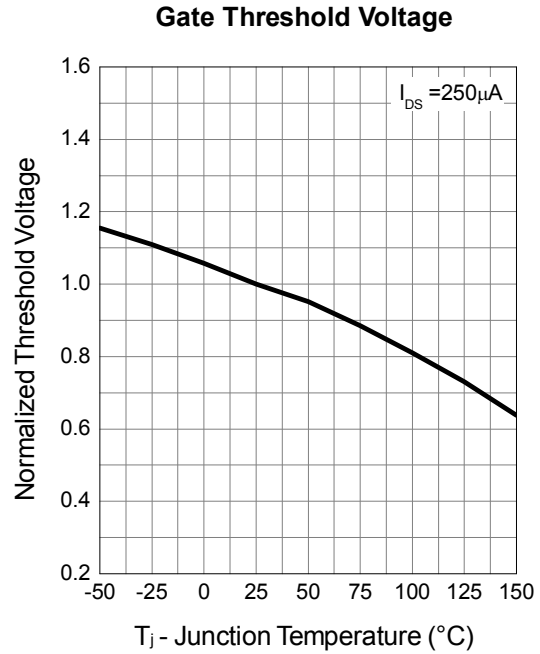
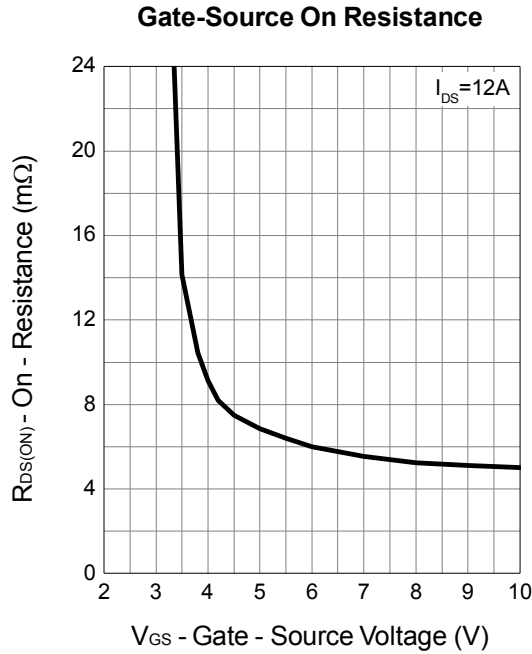
**Safe Operation Area**



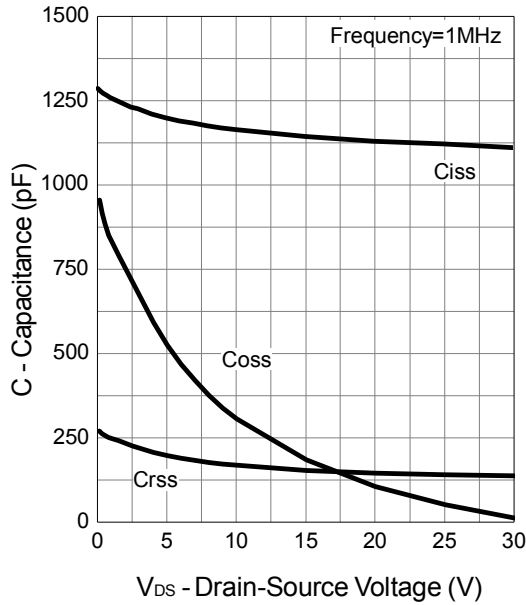
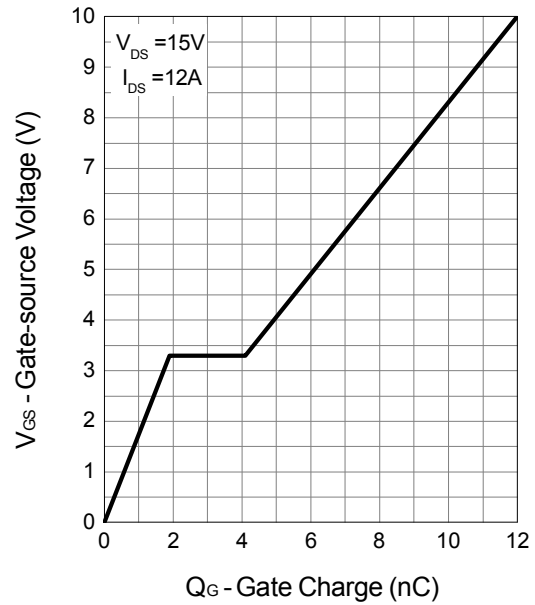
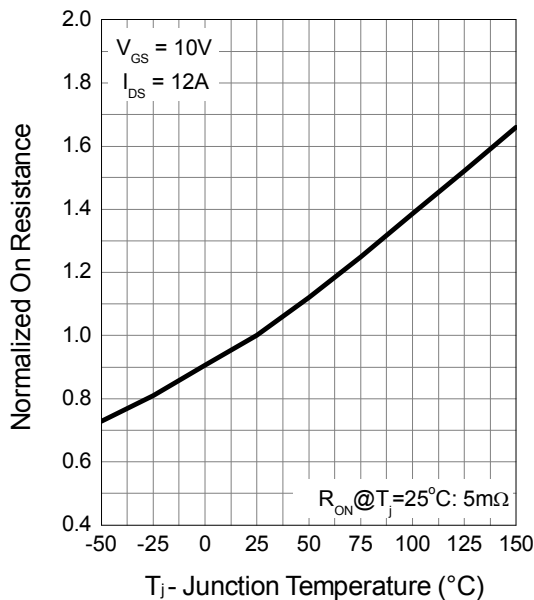
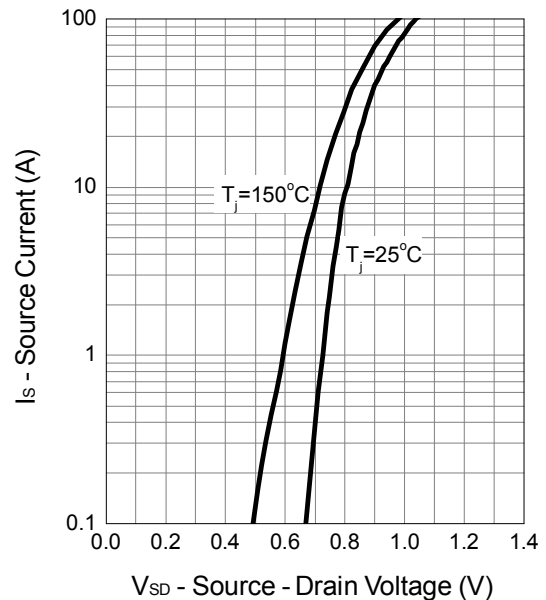
**Thermal Transient Impedance**



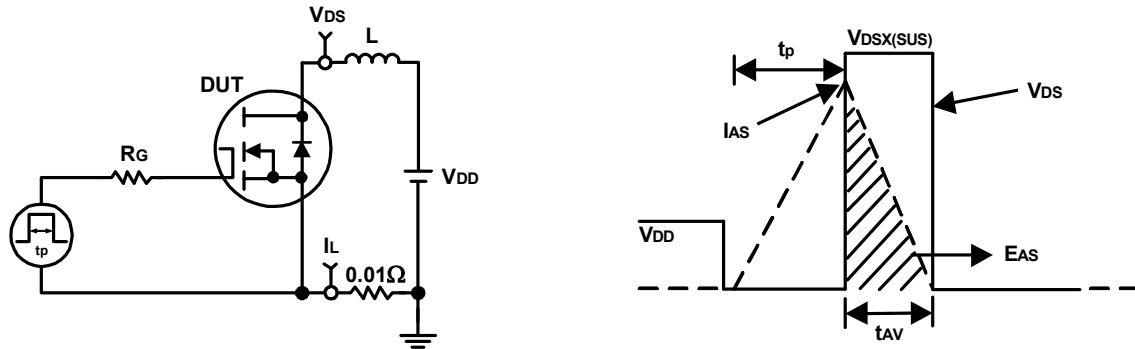
### Typical Operating Characteristics (Cont.)



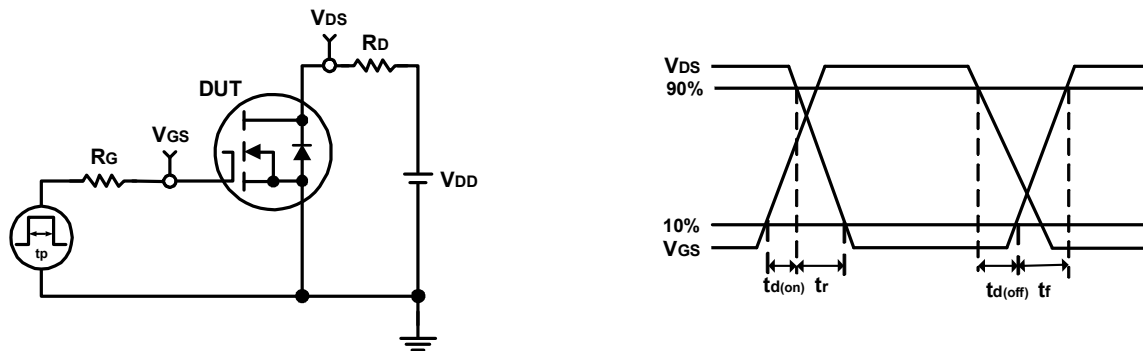
## Typical Operating Characteristics (Cont.)

**Capacitance**

**Gate Charge**

**Drain-Source On Resistance**

**Source-Drain Diode Forward**


### Avalanche Test Circuit and Waveforms

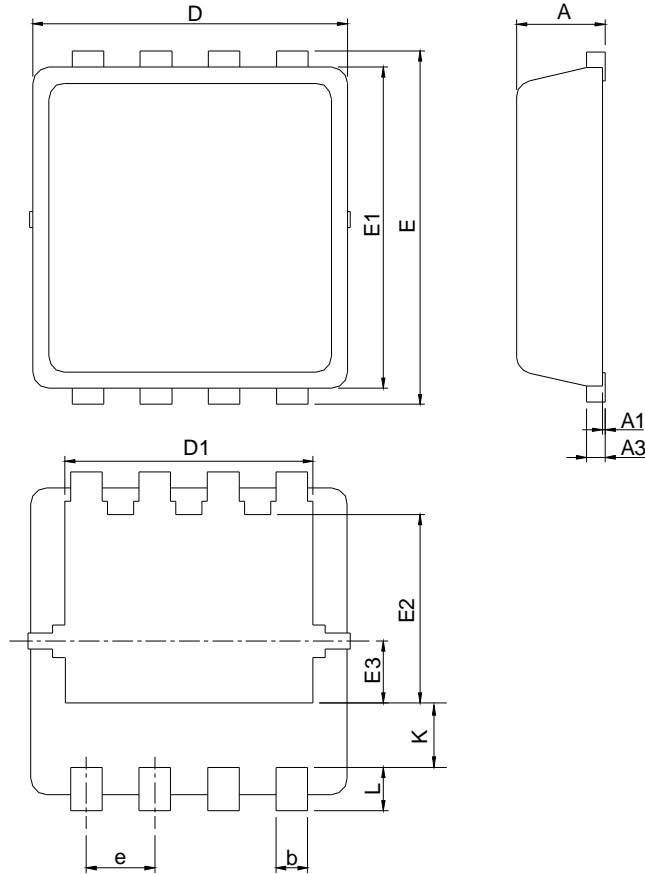


### Switching Time Test Circuit and Waveforms



### Package Information

PDFN3.3\*3.3-8L



SYMBOL	PDFN3.3*3.3-8L			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.031	0.039
A1	0.00	0.05	0.000	0.002
A3	0.10	0.25	0.004	0.010
b	0.24	0.35	0.009	0.014
D	2.90	3.10	0.114	0.122
D1	2.25	2.45	0.089	0.096
E	3.10	3.30	0.122	0.130
E1	2.90	3.10	0.114	0.122
E2	1.65	1.85	0.065	0.073
E3	0.56	0.58	0.022	0.023
e	0.65 BSC		0.026 BSC	
K	0.475	0.775	0.019	0.031
L	0.30	0.50	0.012	0.020

### RECOMMENDED LAND PATTERN

